



# NPN SILICON RF TRANSISTOR NE46234 / 2SC4703

## NPN EPITAXIAL SILICON RF TRANSISTOR FOR HIGH-FREQUENCY LOW DISTORTION AMPLIFIER 3-PIN POWER MINIMOLD

### DESCRIPTION

The NE46234 / 2SC4703 is designed for low distortion, low noise RF amplifier operating with low supply voltage ( $V_{CE} = 5\text{ V}$ ). This low distortion characteristic makes it suitable for CATV, tele-communication and other use. It employs surface mount type plastic package, power mini mold (SOT-89).

### FEATURES

- Low distortion, low voltage:  $IM_2 = 55\text{ dBc TYP.}$ ,  $IM_3 = 76\text{ dBc TYP.}$  @  $V_{CE} = 5\text{ V}$ ,  $I_c = 50\text{ mA}$ ,  $V_o = 105\text{ dB}\mu\text{V}/75\Omega$
- Large  $P_{tot}$  :  $P_{tot} = 1.8\text{ W}$  (Mounted on double-sided copper-clad  $16\text{ cm}^2 \times 0.7\text{ mm}$  (t) ceramic substrate)
- Small package : 3-pin power mini mold package

### ORDERING INFORMATION

Part Number	Quantity	Supplying Form
NE46234-AZ 2SC4703	25 pcs (Non reel)	• 12 mm wide embossed taping
NE46234-T1-AZ 2SC4703-T1	1 kpcs/reel	• Collector face the perforation side of the tape

**Remark** To order evaluation samples, contact your nearby sales office.  
The unit sample quantity is 25 pcs.

### ABSOLUTE MAXIMUM RATINGS ( $T_A = +25^\circ\text{C}$ )

Parameter	Symbol	Ratings	Unit
Collector to Base Voltage	$V_{CBO}$	25	V
Collector to Emitter Voltage	$V_{CEO}$	12	V
Emitter to Base Voltage	$V_{EBO}$	2.5	V
Collector Current	$I_c$	150	mA
Total Power Dissipation	$P_{tot}$ <sup>Note</sup>	1.8	W
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-65 to +150	$^\circ\text{C}$

**Note** Mounted on double-sided copper-clad  $16\text{ cm}^2 \times 0.7\text{ mm}$  (t) ceramic substrate

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C)**

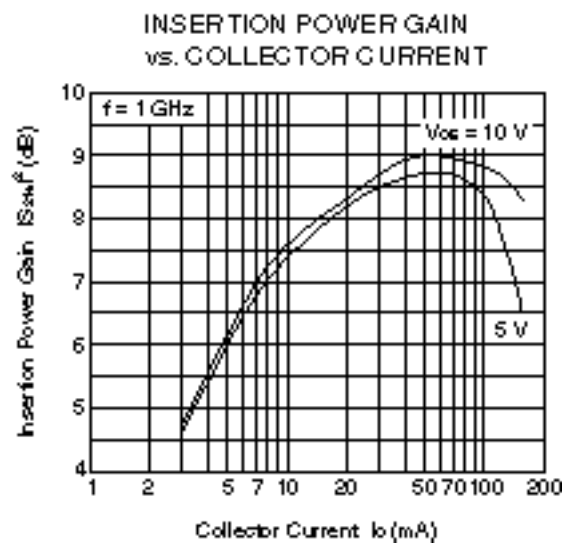
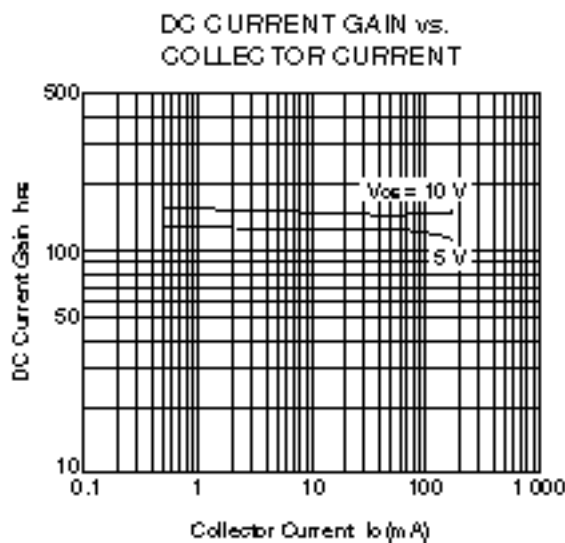
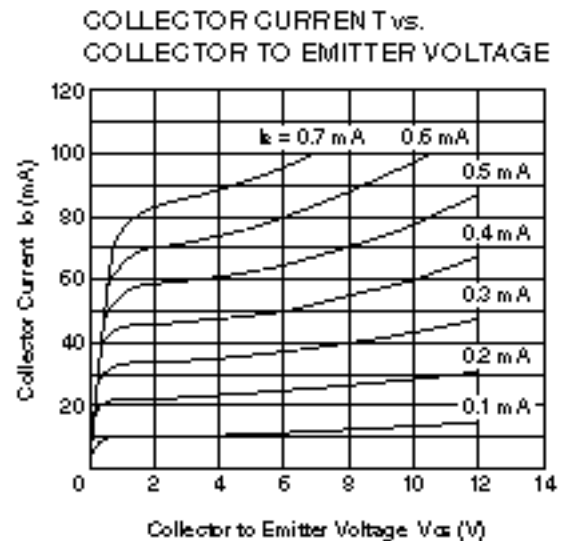
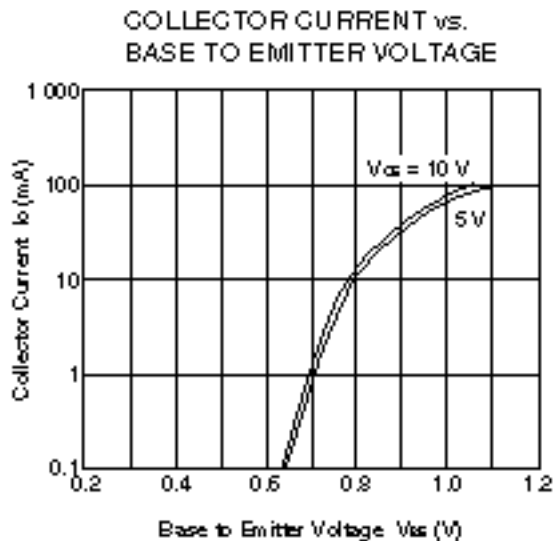
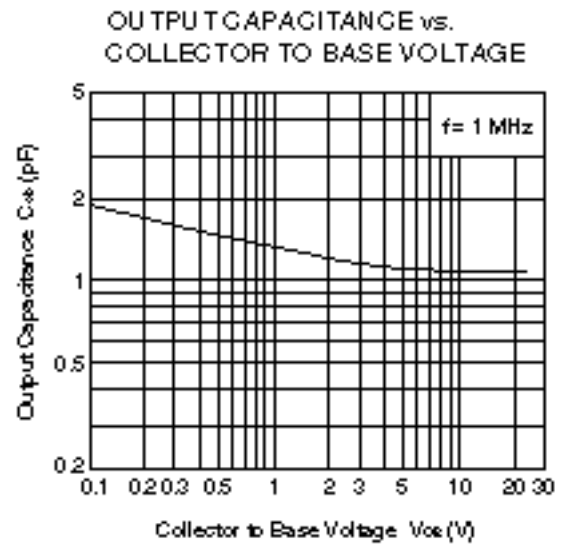
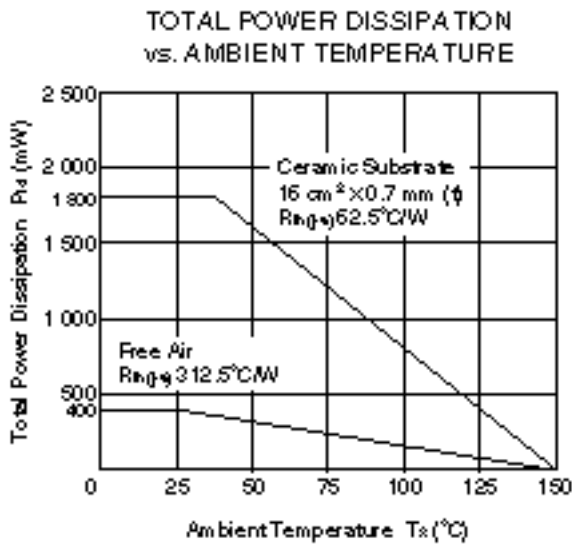
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit	
DC Characteristics							
Collector Cut-off Current	I <sub>CBO</sub>	V <sub>CB</sub> = 20 V, I <sub>E</sub> = 0 mA	–	–	1.5	μA	
Emitter Cut-off Current	I <sub>EBO</sub>	V <sub>EB</sub> = 2 V, I <sub>C</sub> = 0 mA	–	–	1.5	μA	
DC Current Gain	h <sub>FE</sub> <sup>Note 1</sup>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 50 mA	50	–	250	–	
RF Characteristics							
Gain Bandwidth Product	f <sub>T</sub>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 50 mA	–	6.0	–	GHz	
Insertion Power Gain (1)	S <sub>21e</sub>   <sup>2</sup>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 50 mA, f = 1 GHz	6.5	8.3	–	dB	
Insertion Power Gain (2)	S <sub>21e</sub>   <sup>2</sup>	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 20 mA, f = 1 GHz	–	8.5	–	dB	
Noise Figure	NF	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 50 mA, f = 1 GHz	–	2.3	3.5	dB	
Collector Capacitance	C <sub>ob</sub> <sup>Note 2</sup>	V <sub>CB</sub> = 5 V, I <sub>E</sub> = 0 mA, f = 1 MHz	–	1.5	2.5	pF	
2nd Order Intermodulation Distortion	IM <sub>2</sub>	I <sub>C</sub> = 50 mA, V <sub>O</sub> = 105 dBμV/75 Ω, f = 190 – 90 MHz	V <sub>CE</sub> = 5 V	–	55	–	dBc
			V <sub>CE</sub> = 10 V	–	63	–	
3rd Order Intermodulation Distortion	IM <sub>3</sub>	I <sub>C</sub> = 50 mA, V <sub>O</sub> = 105 dBμV/75 Ω, f = 2 × 190 – 200 MHz	V <sub>CE</sub> = 5 V	–	76	–	dBc
			V <sub>CE</sub> = 10 V	–	81	–	

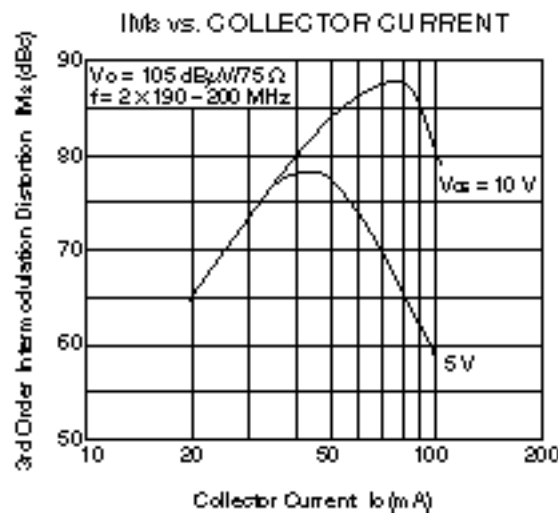
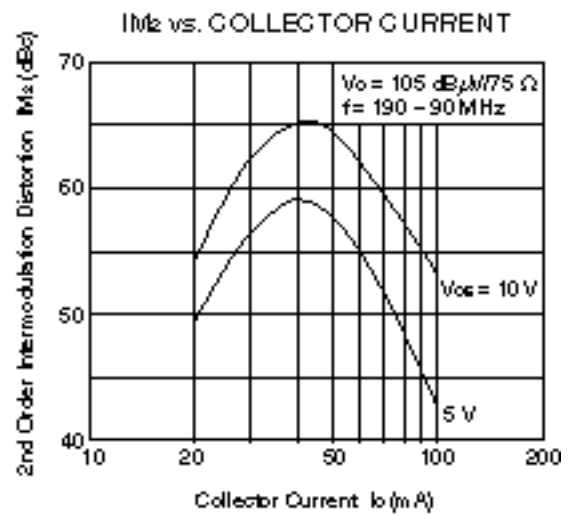
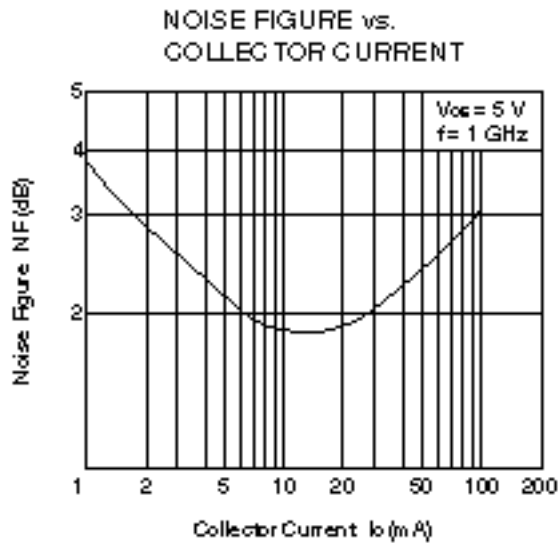
- Notes 1.** Pulse measurement: PW ≤ 350 μs, Duty Cycle ≤ 2%  
**2.** Collector to base capacitance when the emitter grounded

**h<sub>FE</sub> CLASSIFICATION**

Rank	SH	SF	SE
Marking	SH	SF	SE
h <sub>FE</sub> Value	50 to 100	80 to 160	125 to 250

■ TYPICAL CHARACTERISTICS (T<sub>A</sub> = +25°C)





**Remark** The graphs indicate nominal characteristics.

**S-PARAMETERS**

S-parameters/Noise parameters are provided on the NEC Compound Semiconductor Devices Web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

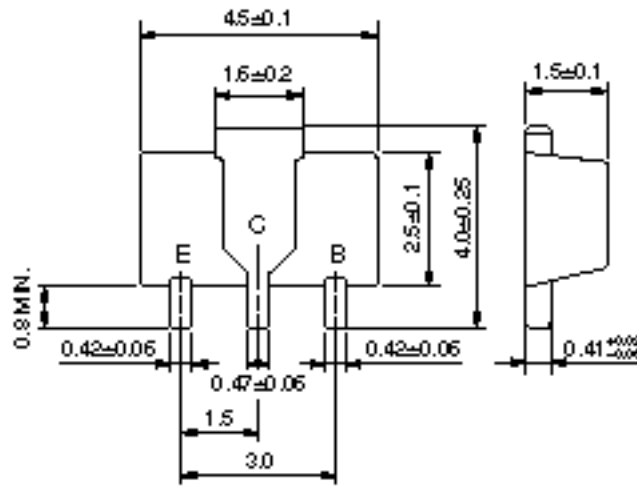
Click here to download S-parameters.

[RF and Microwave] → [Device Parameters]

URL <http://www.csd-nec.com/>

■ PACKAGE DIMENSIONS

3-PIN POWER MINIMOLD (UNIT: mm)



PIN CONNECTIONS

- E : Emitter
- C : Collector (Fin)
- B : Base

(IEC : SOT-89)

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